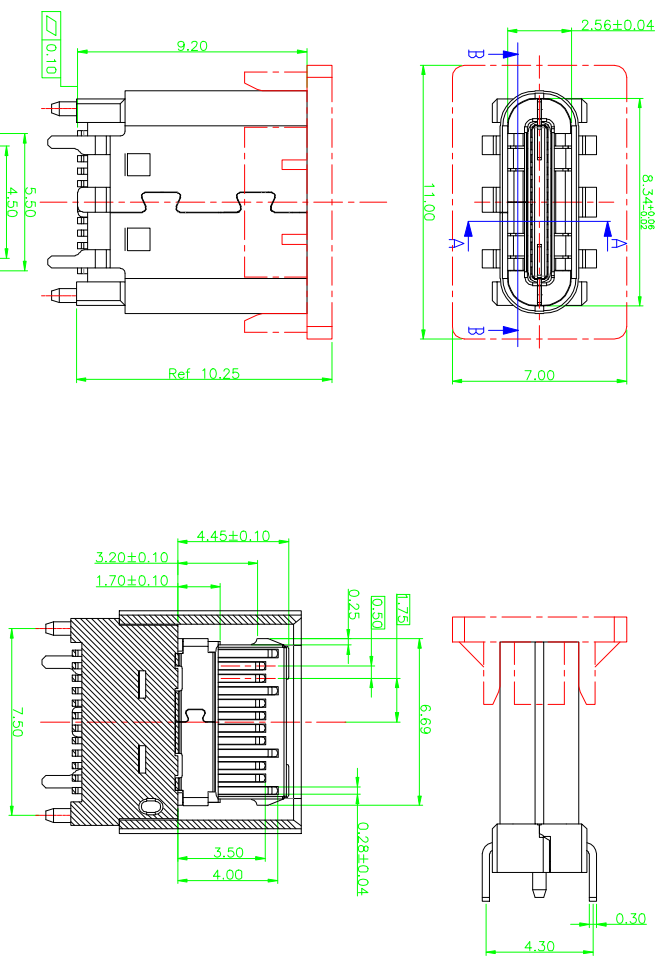
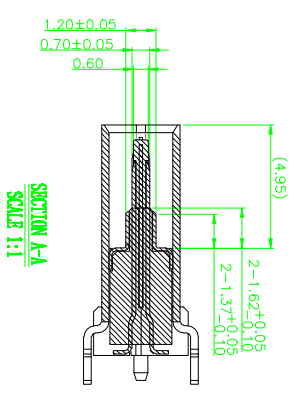
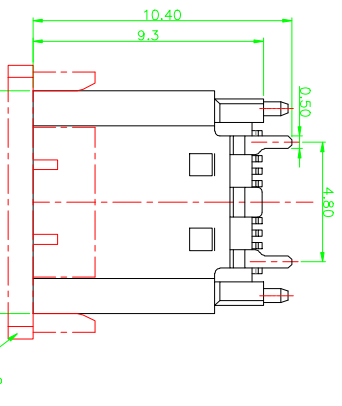


目錄 MAPX	變更內容 MODIFICATION	日期 DATE
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NOTES:
 1.MATERIAL:
 MOLDING: LCP UL94 V-0
 CONTACT: COPPER ALLOY.
 GOLD PLATED 30u" Min ON CONTACT AREA, 100u"
 Min TIN (LEAD FREE) ON SOLDER AREA,
 SHELL: SUS304-H,T=0.30±0.03mm
 50u" NICKEL PLATING OVER ALL.
 SHILD: SUS304-H,T=0.12±0.03mm

2.MECHANICAL:
 INSERTION: 5~20N.
 EXTRACTION: 8~20N.
 DURABILITY: 10000 CYCLES

3.ELECTRICAL:
 CURRENT: 5A MIN FOR VBUS;
 0.25A MIN FOR OTHER.
 VOLTAGE: 5VAC MAX
 WITHSTANDING VOLTAGE: 100V AC.
 CONTACT RESISTANCE: 40mΩ MAX.
 INSULATION RESISTANCE: 100MΩ MIN.

4.ENVIRONMENTAL
 TEMPERATURE RANGE -55°C ~ +85°C

产品图
PRODUCT CHART DWG

深圳市精拓金电子有限公司

公差一览表 TOLERANCE UNLESS OTHERWISE		单位 UNITS	mm	制图 DRAWING	Z-Y-B	产品料号 PRODUCT PART NO.
X	±0.25	X	±.5'	审核 CHECK		产品名称 PRODUCT NO.
XX	±0.20	X'	±.2'	核准 APPRO		USB 3.1 C TYPE 母头180度贴板
XXX	±0.15	XX'	±.1'	日期 DATE	2015.07.30	角法 VIEW
	±0.10	.XXX'	±0.5'			版本 VER
						A0